

IEEE Components, Packaging and Manufacturing Technology Society – OC Chapter

Tuesday, March 3, 2015 Technical Meeting

Copper Pillar VS. Solder Bump: Which is More Reliable?**Craig Hillman, PhD**

CEO and managing partner of DfR Solutions

Abstract

With the need for decreasing pitch and higher current densities, copper pillar has surged to the front in regards to the preferred interconnect methodology for flip chip architectures. However, while there are substantial benefits to copper pillar, there can be some misunderstandings as to the risks of copper pillar, especially under certain manufacturing conditions and field environments. In this presentation, Dr. Hillman will present the current state of copper pillar, review the variations in copper pillar offered by the marketplace, and discuss the current knowledge in regards to copper pillar reliability.

Biography

Craig Hillman, Ph.D., CEO and managing partner of DfR Solutions, is an expert in the development and implementation of strategic reliability processes and operations. His specialties include best practices in Design for Reliability (DfR), strategies for transition to Pb-Free, supplier qualification, accelerated test plan development, and root-cause analysis of component, interconnect, and printed board failures. Dr. Hillman has over 45 publications and has presented on a wide variety of quality and reliability issues to over 250 companies and organizations, including Apple, Dell, Hewlett Packard, Motorola, IBM, Cisco Systems, General Electric, Emerson Electric, Lockheed Martin, Northrop Grumman, Raytheon, Honeywell, and General Dynamics.

Over the past four years, Dr. Hillman has led DfR Solutions through tremendous growth into one of the largest and best-known reliability organizations in the international electronics marketplace.

Date: **Tuesday, March 03, 2015**

Location: **Broadcom Corporation, 5300 California Ave., Irvine, CA 92617 – Salt Creek in Bldg. 2 First Floor**
Check in at the Security Gate and proceed to Bldg. 2. You will be escorted into the building.

Time: **5:30-6:00pm: Social time, 6:00-7:00pm: Presentation, 7:00pm: Dinner (free for attendees!)**

RSVP: **IEEE members and non-members all are welcome. Please RSVP at <http://tinyurl.com/pvmmn5m>**
Please be at the Bldg. 2 entrance by 6:00 pm; no escorts after that. For questions regarding RSVP, please contact Zijie Cai (zijiecai@broadcom.com).

For more information please contact the following officers of the IEEE CPMT OC Chapter:

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